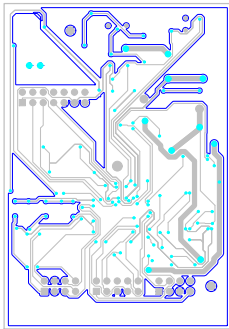
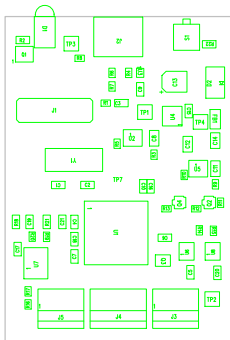


L1





L1

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NOTES: UNLESS OTHERWISE SPECIFIED

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| 1. MATERIAL: | ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BARE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE ROHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0. PLASTIC SHEET, LAMINATED METAL CLAD, ONE OR TWO SIDES, BASE MATERIAL NEMA TYPE FR-4 OR |
| 2. BASE LAMINATE: | EQUIVALENT, W/Tg =140 Deg C OR HIGHER. MINIMUM COMPOSITION TEMP (Td) OF 320 Deg c. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH 2 LAYER STACK-UP, COMPLIANT WITH LEAD FREE PROCESS. |
| 3. SOLDERMASK: | SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB AND OR ASSEMBLY IS ALLOWED PROVIDED NO DEFECTS ARE CREATED TO FINAL ASSEMBLY AS A RESULT. |
| 4. TOLERANCES: | UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE +/- .005 INCHES, HOLE DIAMETERS SHALL BE +/- .003 INCHES. |
| 5. PLATING: | HOLES REQUIRING PLATING, SEE HOLE CHART, TO HAVE 1 OZ. (0.0014) MIN. THK MIN. THICK COPPER. |
| 6. FINISH: | PLATE WITH ROHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION TIN OR Sn/Ag/Cu, WITH RMA FLUX 0.0003" TO .0005" THICK ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE. |
| 7. LEGEND: | IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK. |
| 8. MARKINGS: | BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL. |
| 9. WORKMANSHIP: | BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER. |
| 10. DOCUMENTATION: | PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER. |
| 11. DRILL SIZES: | HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED. |
| 12. PANEL BORDER: | ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK. |
| 13. PROCESS CHANGES: | NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS. |